	Туре	L#	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	22	Yuan-ping.in.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/04/24 14:15
2	IS&R	L2	11	(("20010009301") or ("5942794") or ("5157457") or ("6483178") or ("6424024") or ("6400004")).PN.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/04/24 16:59
3	IS&R	L3	2	("5157475").PN.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/04/24 15:04
4	IS&R	L4	1	("6548328").PN.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/04/24 15:04
5	IS&R	L5	2	("5752182").PN.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/04/24 17:04

	Туре	L #	Hits	Search Text	DBs	Time Stamp
6	IS&R	L6	2	("6399415").PN.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/04/24 17:05
7	BRS	Ь7	16	(seal\$4 adj resin) near2 magnetic	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/04/24 17:59
8	BRS	L8	170	multi adj substrate	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/04/24 18:24
9	IS&R	L9	4	(("6399415") or ("5741729")).PN.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/04/24 18:24

-	/	Bayan-jaime.in.	USPAT;	2003/04/23
			US-PGPUB; EPO; JPO;	13:22
			DERWENT;	
			IBM TDB	
_	26	("5157475" "5157480" "5367196"	USPAT	2003/04/23
		"5454905" "5494207" "5508556"	001	13:09
		"5521429" "5596231" "5623123"		
		"5656550" "5741729" "5844315"		
		"5854511" "5866948" "5981314"		
		"5990545" "6013946" "6060774"		
		"6060778" "6093960" "6130473"		
		"6133070" "6177288" "6188130"	Ì	
	170	"6201292" "6215179").PN.		000040440
-	170	ueno-yutaka.in.	USPAT;	2003/04/23
			US-PGPUB; EPO; JPO;	14:00
			DERWENT;	
			IBM TDB	
_	247	257/711,684,730-731.ccls. and substrate	USPAT;	2003/04/23
		and (groove concave trench\$4 recess\$4)	US-PGPUB;	15:13
		.,	EPO; JPO;	
			DERWENT;	
1			IBM_TDB	
-	676	, , , , , , , , , , , , , , , , , , , ,	USPAT;	2003/04/23
		substrate and (groove concave trench\$4	US-PGPUB;	14:21
		recess\$4)	EPO; JPO;	
			DERWENT;	
_	34	257/782-784,787-789,796.ccls. and	IBM_TDB USPAT;	2003/04/23
		substrate with (metal adj layer) and	US-PGPUB;	14:26
		(groove concave trench\$4 recess\$4)	EPO; JPO;	11.20
			DERWENT;	
			IBM_TDB	
-	5023		USPAT;	2003/04/23
		(groove concave trench\$4 recess\$4)	US-PGPUB;	14:44
			EPO; JPO;	
			DERWENT;	
_	1909	substrate with (metal adj layer) and	IBM_TDB USPAT;	2003/04/23
	1303	(groove concave trench\$4 recess\$4) and	US-PGPUB;	14:46
		257/\$.ccls.	EPO; JPO;	11.10
			DERWENT;	
			IBM TDB	
-	3832	, , , , , , , , , , , , , , , , , , , ,	USPAT;	2003/04/23
		(groove concave trench\$4 recess\$4) and	US-PGPUB;	15:03
		semiconductor	EPO; JPO;	
			DERWENT;	
_	724	 substrate with (metal adj laver) with	IBM_TDB USPAT;	2003/04/23
	'24	(groove concave trench\$4 recess\$4) and	US-PGPUB;	15:05
		semiconductor	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	4	- · · · · · · · · · · · · · · · · · ·	USPAT;	2003/04/23
		adj substrate) and (groove concave	US-PGPUB;	15:16
1		trench\$4 recess\$4)	EPO; JPO;	
1			DERWENT;	
_	427	(multilayer adj substrate) and (groove	IBM_TDB USPAT;	2003/04/23
	12/	concave trench\$4 recess\$4)	US-PGPUB;	15:18
1			EPO; JPO;	
1			DERWENT;	
			IBM_TDB	

	7.	\	T	
_	36		USPAT;	2003/04/09
		("6259161") or ("6288851") or ("6278190")	US-PGPUB;	15:35
		or ("6344682") or ("6184061") or	EPO; JPO;	
		("5986336") or ("5959353") or ("6270202")	DERWENT;	
		or ("5900582") or ("5969463") or	IBM_TDB	
		("5910699") or ("5925973") or ("5724726")		
Ì		or ("5763829") or ("5281818") or		1
		("5291484") or ("4831636")).PN.		
_	429	(reaction adj layer) and laminat\$4	USPAT;	2003/04/09
			US-PGPUB;	16:03
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	66	(= = = = = = = = = = = = = = = = = = =	USPAT;	2003/04/09
		(bump ball)	US-PGPUB;	16:03
			EPO; JPO;	
			DERWENT;	
	1.7	400/605	IBM_TDB	
-	17	438/615.ccls. and laminat\$4 and press\$4	USPAT;	2003/04/09
			US-PGPUB;	16:10
			EPO; JPO;	
]	1		DERWENT;	
	500	420/612 617 3	IBM_TDB	
-	580	438/613-617.ccls. and press\$4 and heat\$4	USPAT;	2003/04/09
			US-PGPUB;	16:19
			EPO; JPO;	
			DERWENT;	
	400	420 /612 617 1	IBM_TDB	
-	488		USPAT;	2003/04/09
		and (bump ball) and (chip die IC	US-PGPUB;	16:23
		substrate)	EPO; JPO;	
			DERWENT;	
1	0		IBM_TDB	
-	"	((constant and) sugger (restricted and)	USPAT;	2003/04/09
i :		tomita)) and press\$4 and heat\$4 and (bump	US-PGPUB;	17:02
		ball) and (chip die IC substrate)	EPO; JPO;	
			DERWENT;	
_	5	**************************************	IBM_TDB	0000/01/00
		tago-masamoto.in. and heat\$4 and press\$4	USPAT; US-PGPUB;	2003/04/09
			EPO; JPO;	17:11
			DERWENT; IBM TDB	
_	2	tago-masamoto.in. and	USPAT;	2003/04/09
		Tomita-yoshihiro.in. and heat\$4 and	US-PGPUB;	17:12
		press\$4	EPO; JPO;	11.16
		F	DERWENT;	
			IBM TDB	
	27	Tomita-yoshihiro.in. and heat\$4 and	USPAT;	2003/04/10
	"	press\$4	US-PGPUB;	15:18
		F1-	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	24	(("5229647") or ("5418687") or	USPAT;	2003/04/10
		("5440241") or ("5506383") or ("5682062")	US-PGPUB;	15:56
		or ("5685885") or ("5742100") or	EPO; JPO;	
		("5767575") or ("5892288") or ("5973396")	DERWENT;	
		or ("5990546") or ("6004867")).PN.	IBM TDB	
-	3	("3171643").PN.	USPAT;	2003/04/14
		• • • • • • • • • • • • • • • • • • • •	US-PGPUB;	11:47
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	2	("2002170919").PN.	USPAT;	2003/04/14
		•	US-PGPUB;	11:47
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
	·			

-	1	irradiating adj radical adj fluorine	USPAT;	2003/04/09
			US-PGPUB;	14:26
			EPO; JPO;	
			DERWENT;	
		1 1 644 12 12 1 12 63	IBM_TDB	0000/04/00
-	1	irradiat\$4 adj radical adj fluorine	USPAT;	2003/04/09
			US-PGPUB;	14:26
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	0	activating and sputerring	USPAT;	2003/04/09
		·	US-PGPUB;	14:27
			EPO; JPO;	
			DERWENT;	
	_		IBM_TDB	
-	9	activat\$4 and sputterring	USPAT;	2003/04/09
			US-PGPUB;	14:29
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	0	activat\$4 with sputterring	USPĀT;	2003/04/09
			US-PGPUB;	14:29
			EPO; JPO;	
			DERWENT;	1
			IBM TDB	
_	0	sputterr\$4 and (reduction adj gas)	USPAT;	2003/04/09
			US-PGPUB;	14:30
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	1 0	sputterr\$4 and (reduct\$4 adj gas)	USPĀT;	2003/04/09
	_		US-PGPUB;	14:40
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	2	("2002110726").PN.	USPAT;	2003/04/09
		(2002220,200) 12111	US-PGPUB;	14:56
			EPO; JPO;	11.00
			DERWENT;	
:			IBM TDB	
_	133	multi-layer and solder and intermetallic	USPAT;	2003/04/09
	155	marci layer and border and incomerative	US-PGPUB;	15:04
			EPO; JPO;	10.01
			DERWENT;	
			IBM TDB	
1_	1602	 solder and intermetallic	USPAT;	2003/04/09
	1003	SOLUCE AND INTELLICUALITY	US-PGPUB;	15:04
			EPO; JPO;	10.01
			DERWENT;	
			IBM TDB	
_	581	 solder and intermetallic and (bump ball)	USPAT;	2003/04/09
1	361	sorder and intermedatite and (namb part)	US-PGPUB;	15:05
			EPO; JPO;	10.00
			DERWENT;	
			IBM TDB	
	210	solder and intermetallic and (bump ball)	USPAT;	2003/04/09
-	310		1	15:18
		and press\$4 and (heat\$4 reflow\$4)	US-PGPUB;	15.10
			EPO; JPO;	
	1		DERWENT;	
	_	(/#5244506#) (#5522024#)	IBM_TDB	3003/04/00
-	6	' ' ' ' ' ' ' ' ' ' ' ' ' '	USPAT;	2003/04/09
		("5508561")).PN.	US-PGPUB;	15:27
			EPO; JPO;	
	1		DERWENT;	
	1		IBM_TDB	

L Number	Hits	Search Text	DB	Time stamp
-	4	257/737-738.ccls. and (bump ball) and (supersonic adj wave)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/04/09 13:37
-	1	257/779.ccls. and (bump ball) and (supersonic adj wave)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/04/09 13:38
_	0	257/685-686.ccls. and (bump ball) and (supersonic adj wave)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/04/09 13:39
-	577	257/685-686.ccls. and (bump ball)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/09 13:43
_	0	257/685-686.ccls. and (supersonic adj wave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/09 13:44
_	128	257/685-686.ccls. and laminat\$4 and press\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/09 13:54
-	157	438/613-617.ccls. and laminat\$4 and press\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/09
_	90	438/612.ccls. and laminat\$4 and press\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/09 14:14
-	419	438/612.ccls. and ((irrfaiating adj radical adj fluorine) (reduction adj gas) sputter\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/09 14:16
_	136	438/612.ccls. and ((irrfaiating adj radical adj fluorine) (reduction adj gas) sputter\$4) and press\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/09 14:22
-	1	(atomic adj beam) with (inactive adj gas adj excited) near3 plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/09 14:23
_	1	(atomic adj beam) with (inactive adj gas adj excited) with plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/09 14:24
_	1	(atomic adj beam) and (inactive adj gas adj excited) and plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:25